To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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# HM62V8512B Series

4 M SRAM (512-kword × 8-bit)

ADE-203-905G (Z)
Rev. 6.0
Mar. 31, 2000

## Description

The Hitachi HM62V8512B is a 4-Mbit static RAM organized 512-kword × 8-bit. It realizes higher density, higher performance and low power consumption by employing 0.35 µm Hi-CMOS process technology. The device, packaged in a 525-mil SOP (foot print pitch width) or 400-mil TSOP TYPE II is available for high density mounting. The HM62V8512B is suitable for battery backup system.

## Features

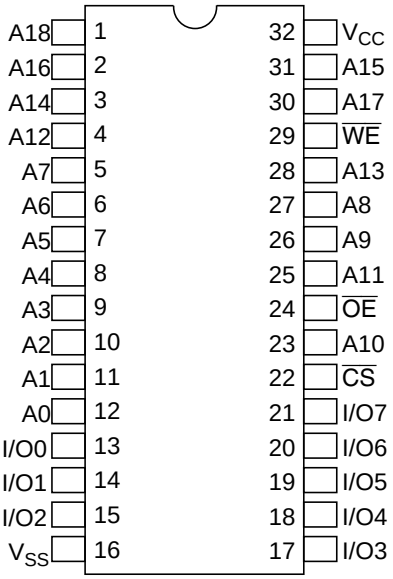
- Single 3.0 V supply: 2.7 V to 3.6 V
- Access time: 70/85 ns (max)
- Power dissipation
  - Active: 15 mW/MHz (typ)
  - Standby: 3 µW (typ)
- Completely static memory. No clock or timing strobe required
- Equal access and cycle times
- Common data input and output: Three state output
- Directly LV-TTL compatible: All inputs
- Battery backup operation

## Ordering Information

| Type No. | Access time | Package |
|---|---|---|
| HM62V8512BLFP-7 | 70 ns | 525-mil 32-pin plastic SOP (FP-32D) |
| HM62V8512BLFP-8 | 85 ns | |
| HM62V8512BLFP-7SL | 70 ns | |
| HM62V8512BLFP-8SL | 85 ns | |
| HM62V8512BLFP-7UL | 70 ns | |
| HM62V8512BLFP-8UL | 85 ns | |
| HM62V8512BLTT-7 | 70 ns | 400-mil 32-pin plastic TSOP II (TTP-32D) |
| HM62V8512BLTT-8 | 85 ns | |
| HM62V8512BLTT-7SL | 70 ns | |
| HM62V8512BLTT-8SL | 85 ns | |
| HM62V8512BLTT-7UL | 70 ns | |
| HM62V8512BLTT-8UL | 85 ns | |
| HM62V8512BLRR-7 | 70 ns | 400-mil 32-pin plastic TSOP II reverse (TTP-32DR) |
| HM62V8512BLRR-8 | 85 ns | |
| HM62V8512BLRR-7SL | 70 ns | |
| HM62V8512BLRR-8SL | 85 ns | |
| HM62V8512BLRR-7UL | 70 ns | |
| HM62V8512BLRR-8UL | 85 ns | |

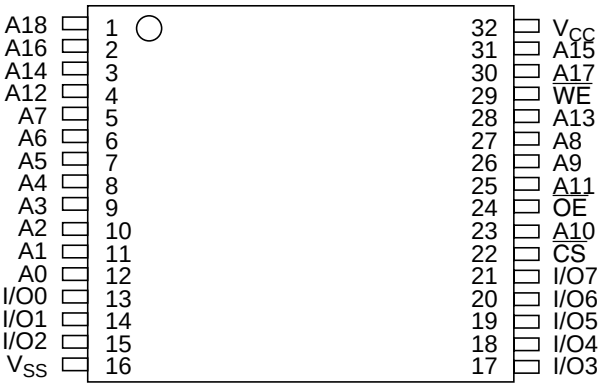
## Pin Arrangement

HM62V8512BLFP Series



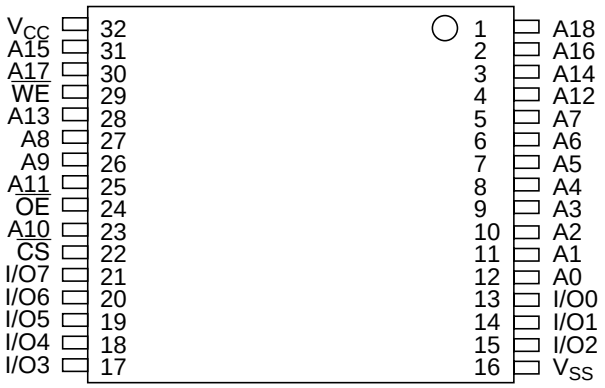

(Top view)

HM62V8512BLTT Series




(Top view)

HM62V8512BLRR Series

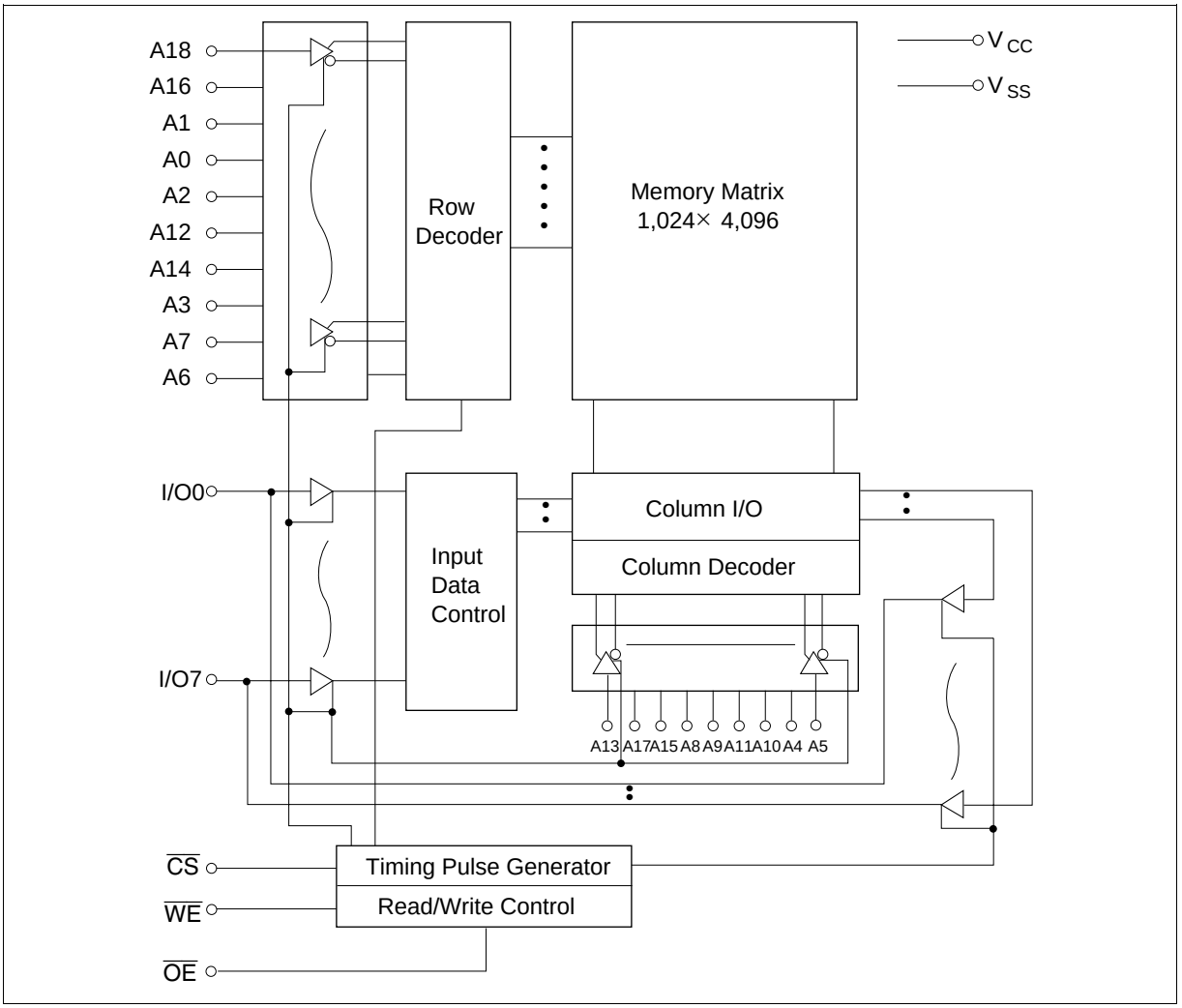



(Top view)

## Pin Description

| Pin name | Function |
|---|---|
| A0 to A18 | Address input |
| I/O0 to I/O7 | Data input/output |
| $\overline{CS}$ | Chip select |
| $\overline{OE}$ | Output enable |
| $\overline{WE}$ | Write enable |
| $V_{CC}$ | Power supply |
| $V_{SS}$ | Ground |

## Block Diagram



## Function Table

| $\overline{WE}$ | $\overline{CS}$ | $\overline{OE}$ | Mode | $V_{CC}$ current | Dout pin | Ref. cycle |
|---|---|---|---|---|---|---|
| × | H | × | Not selected | $I_{SB}$, $I_{SB1}$ | High-Z | — |
| H | L | H | Output disable | $I_{CC}$ | High-Z | — |
| H | L | L | Read | $I_{CC}$ | Dout | Read cycle |
| L | L | H | Write | $I_{CC}$ | Din | Write cycle (1) |
| L | L | L | Write | $I_{CC}$ | Din | Write cycle (2) |

Note: ×: H or L

## Absolute Maximum Ratings

| Parameter | Symbol | Value | Unit |
|---|---|---|---|
| Power supply voltage | $V_{CC}$ | –0.5 to +4.6 | V |
| Voltage on any pin relative to $V_{SS}$ | $V_T$ | –0.5*[1] to $V_{CC}$ + 0.5*[2] | V |
| Power dissipation | $P_T$ | 1.0 | W |
| Operating temperature | Topr | –20 to +70 | °C |
| Storage temperature | Tstg | –55 to +125 | °C |
| Storage temperature under bias | Tbias | –20 to +85 | °C |

Notes: 1. –3.0 V for pulse half-width ≤ 30 ns
2. Maximum voltage is 4.6 V

## Recommended DC Operating Conditions (Ta = –20 to +70°C)

| Parameter | Symbol | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| Supply voltage | $V_{CC}$ | 2.7 | 3.0 | 3.6 | V |
| | $V_{SS}$ | 0 | 0 | 0 | V |
| Input high voltage | $V_{IH}$ | 2.0 | — | $V_{CC}$ + 0.3 | V |
| Input low voltage | $V_{IL}$ | –0.3*[1] | — | 0.8 | V |

Note: 1. –3.0 V for pulse half-width ≤ 30 ns

## DC Characteristics (Ta = –20 to +70°C, $V_{CC}$ = 2.7 V to 3.6 V, $V_{SS}$ = 0 V)

| Parameter | Symbol | Min | Typ*[1] | Max | Unit | Test conditions |
|---|---|---|---|---|---|---|
| Input leakage current | $\|I_{LI}\|$ | — | — | 1 | µA | Vin = $V_{SS}$ to $V_{CC}$ |
| Output leakage current | $\|I_{LO}\|$ | — | — | 1 | µA | $\overline{CS}$ = $V_{IH}$ or $\overline{OE}$ = $V_{IH}$ or $\overline{WE}$ = $V_{IL}$, $V_{I/O}$ = $V_{SS}$ to $V_{CC}$ |
| Operating power supply current: DC | $I_{CC}$ | — | — | 10 | mA | $\overline{CS}$ = $V_{IL}$, others = $V_{IH}$/$V_{IL}$, $I_{I/O}$ = 0 mA |
| Operating power supply current | $I_{CC1}$ | — | — | 40 | mA | Min cycle, duty = 100% $\overline{CS}$ = $V_{IL}$, others = $V_{IH}$/$V_{IL}$ $I_{I/O}$ = 0 mA |
| Operating power supply current | $I_{CC2}$ | — | 5 | 10 | mA | Cycle time = 1 µs, duty = 100% $I_{I/O}$ = 0 mA, $\overline{CS}$ ≤ 0.2 V $V_{IH}$ ≥ $V_{CC}$ – 0.2 V, $V_{IL}$ ≤ 0.2 V |
| Standby power supply current: DC | $I_{SB}$ | — | 0.1 | 0.3 | mA | $\overline{CS}$ = $V_{IH}$ |
| Standby power supply current (1): DC | $I_{SB1}$ | — | 1*[2] | 40*[2] | µA | Vin ≥ 0 V, $\overline{CS}$ ≥ $V_{CC}$ – 0.2 V |
| | | — | 1*[3] | 20*[3] | µA | |
| | | — | 1*[4] | 5*[4] | µA | |
| Output low voltage | $V_{OL}$ | — | — | 0.4 | V | $I_{OL}$ = 2.1 mA |
| | | — | — | 0.2 | V | $I_{OL}$ = 100 µA |
| Output high voltage | $V_{OH}$ | $V_{CC}$ – 0.2 | — | — | V | $I_{OH}$ = –100 µA |
| | | 2.4 | — | — | V | $I_{OH}$ = –1.0 mA |

Notes: 1. Typical values are at $V_{CC}$ = 3.0 V, Ta = +25°C and specified loading, and not guaranteed.
2. This characteristics is guaranteed only for L version.
3. This characteristics is guaranteed only for L-SL version.
4. This characteristics is guaranteed only for L-UL version.

## Capacitance (Ta = +25°C, f = 1 MHz)

| Parameter | Symbol | Typ | Max | Unit | Test conditions |
|---|---|---|---|---|---|
| Input capacitance*[1] | Cin | — | 8 | pF | Vin = 0 V |
| Input/output capacitance*[1] | $C_{I/O}$ | — | 10 | pF | $V_{I/O}$ = 0 V |

Note: 1. This parameter is sampled and not 100% tested.

## AC Characteristics (Ta = –20 to +70°C, $V_{CC}$ = 2.7 V to 3.6 V, unless otherwise noted.)

### Test Conditions

- Input pulse levels: 0.4 V to 2.4 V
- Input rise and fall time: 5 ns
- Input timing reference levels: 1.4 V
- Output timing reference level: 1.5 V/1.5 V(HM62V8512B-7)
  0.8 V/2.0 V(HM62V8512B-8)

  Output load: 1 TTL Gate + $C_L$ (50 pF)
  (Including scope & jig)

### Read Cycle

| | | HM62V8512B | | | | | |
|---|---|---|---|---|---|---|---|
| | | -7 | | -8 | | | |
| **Parameter** | **Symbol** | **Min** | **Max** | **Min** | **Max** | **Unit** | **Notes** |
| Read cycle time | $t_{RC}$ | 70 | — | 85 | — | ns | |
| Address access time | $t_{AA}$ | — | 70 | — | 85 | ns | |
| Chip select access time | $t_{CO}$ | — | 70 | — | 85 | ns | |
| Output enable to output valid | $t_{OE}$ | — | 35 | — | 45 | ns | |
| Chip selection to output in low-Z | $t_{LZ}$ | 10 | — | 10 | — | ns | 2 |
| Output enable to output in low-Z | $t_{OLZ}$ | 5 | — | 5 | — | ns | 2 |
| Chip deselection to output in high-Z | $t_{HZ}$ | 0 | 30 | 0 | 35 | ns | 1, 2 |
| Output disable to output in high-Z | $t_{OHZ}$ | 0 | 30 | 0 | 35 | ns | 1, 2 |
| Output hold from address change | $t_{OH}$ | 10 | — | 10 | — | ns | |

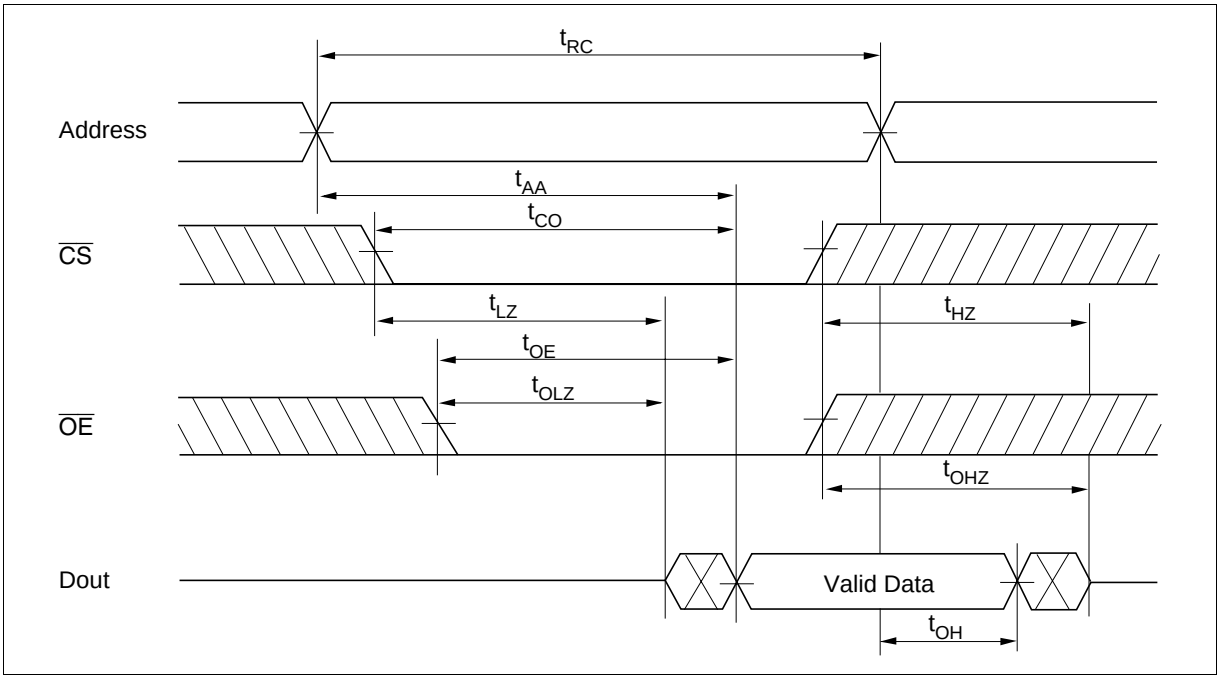
### Write Cycle

| | | HM62V8512B | | | | | |
|---|---|---|---|---|---|---|---|
| | | -7 | | -8 | | | |
| Parameter | Symbol | Min | Max | Min | Max | Unit | Notes |
| Write cycle time | $t_{WC}$ | 70 | — | 85 | — | ns | |
| Chip selection to end of write | $t_{CW}$ | 60 | — | 75 | — | ns | 4 |
| Address setup time | $t_{AS}$ | 0 | — | 0 | — | ns | 5 |
| Address valid to end of write | $t_{AW}$ | 60 | — | 75 | — | ns | |
| Write pulse width | $t_{WP}$ | 50 | — | 55 | — | ns | 3, 12 |
| Write recovery time | $t_{WR}$ | 0 | — | 0 | — | ns | 6 |
| $\overline{WE}$ to output in high-Z | $t_{WHZ}$ | 0 | 30 | 0 | 35 | ns | 1, 2, 7 |
| Data to write time overlap | $t_{DW}$ | 30 | — | 35 | — | ns | |
| Data hold from write time | $t_{DH}$ | 0 | — | 0 | — | ns | |
| Output active from output in high-Z | $t_{OW}$ | 5 | — | 5 | — | ns | 2 |
| Output disable to output in high-Z | $t_{OHZ}$ | 0 | 30 | 0 | 35 | ns | 1, 2, 7 |

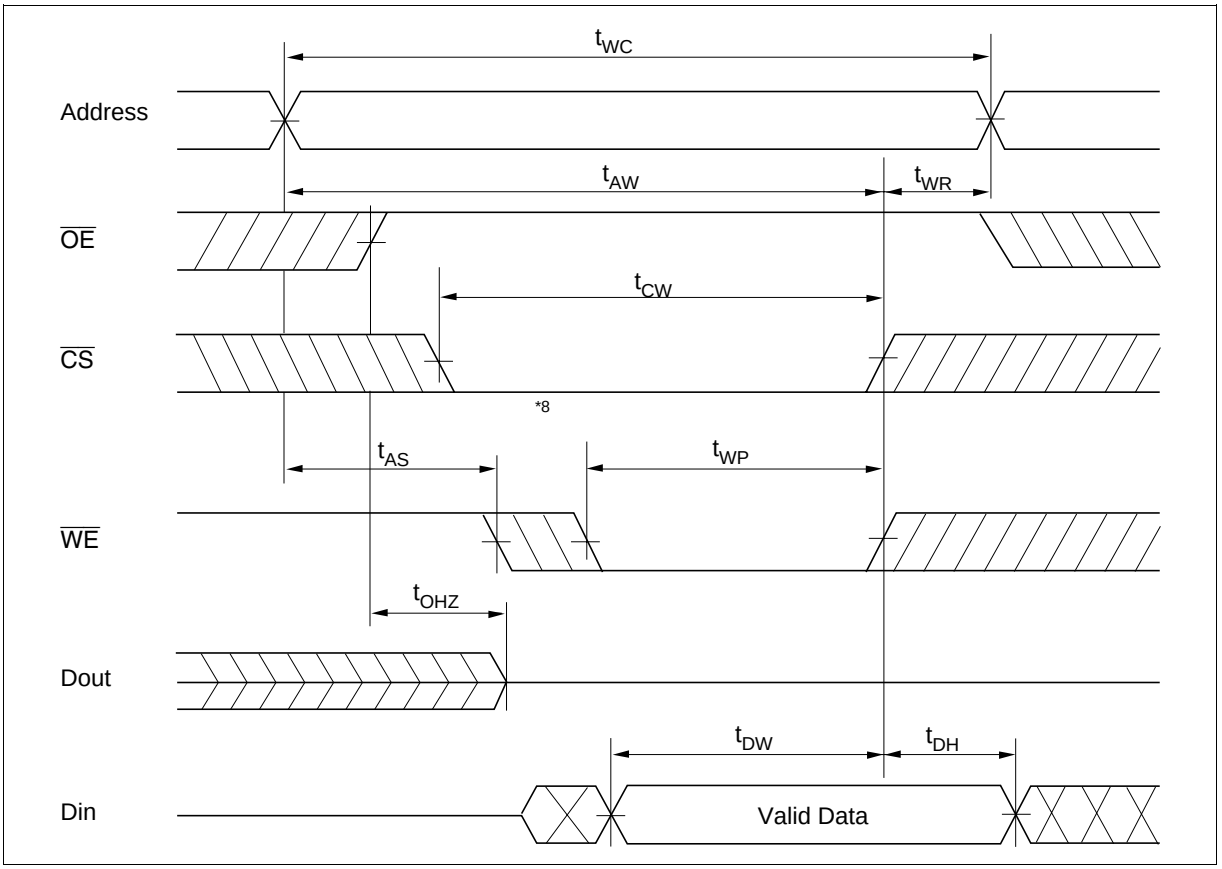
Notes:
1. $t_{HZ}$, $t_{OHZ}$ and $t_{WHZ}$ are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.
2. This parameter is sampled and not 100% tested.
3. A write occurs during the overlap ($t_{WP}$) of a low $\overline{CS}$ and a low $\overline{WE}$. A write begins at the later transition of $\overline{CS}$ going low or $\overline{WE}$ going low. A write ends at the earlier transition of $\overline{CS}$ going high or $\overline{WE}$ going high. $t_{WP}$ is measured from the beginning of write to the end of write.
4. $t_{CW}$ is measured from $\overline{CS}$ going low to the end of write.
5. $t_{AS}$ is measured from the address valid to the beginning of write.
6. $t_{WR}$ is measured from the earlier of $\overline{WE}$ or $\overline{CS}$ going high to the end of write cycle.
7. During this period, I/O pins are in the output state so that the input signals of the opposite phase to the outputs must not be applied.
8. If the $\overline{CS}$ low transition occurs simultaneously with the $\overline{WE}$ low transition or after the $\overline{WE}$ transition, the output remain in a high impedance state.
9. Dout is the same phase of the write data of this write cycle.
10. Dout is the read data of next address.
11. If $\overline{CS}$ is low during this period, I/O pins are in the output state. Therefore, the input signals of the opposite phase to the outputs must not be applied to them.
12. In the write cycle with $\overline{OE}$ low fixed, $t_{WP}$ must satisfy the following equation to avoid a problem of data bus contention. $t_{WP} \geq t_{DW}$ min + $t_{WHZ}$ max

## Timing Waveforms

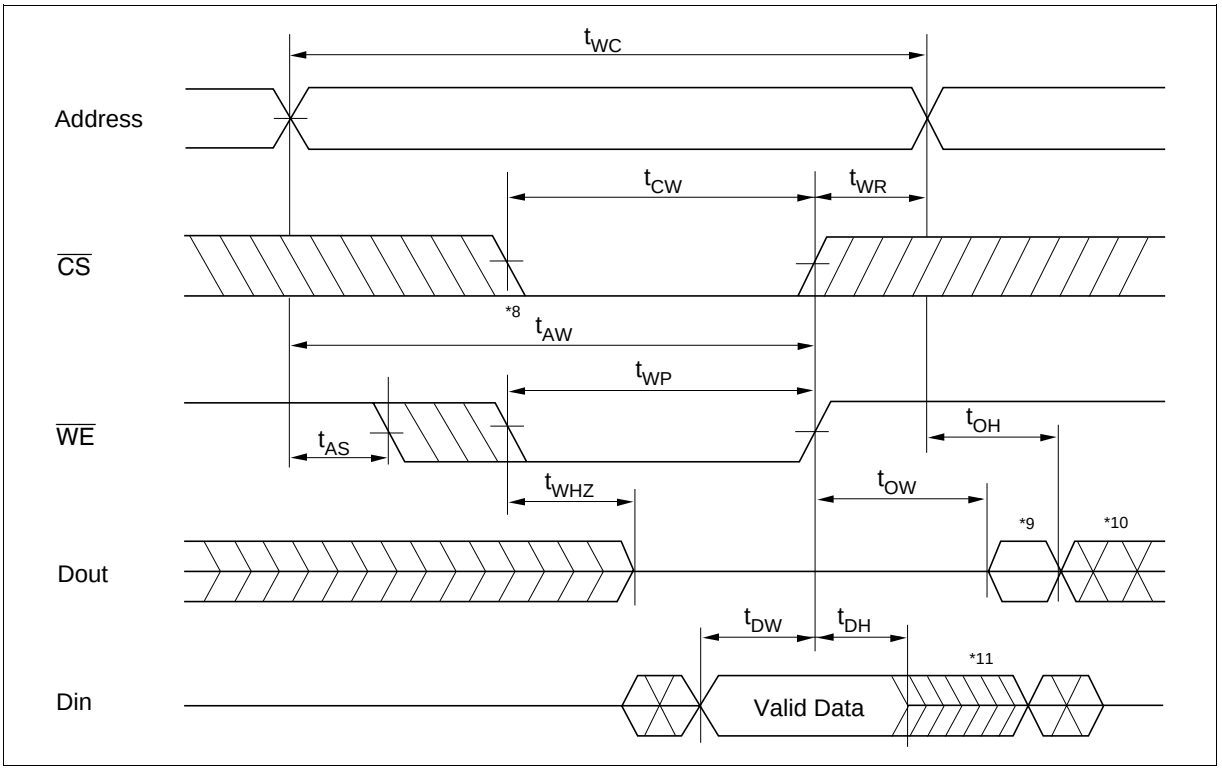
**Read Timing Waveform** ($\overline{WE}$ = $V_{IH}$)



**Write Timing Waveform (1)** ($\overline{OE}$ Clock)



**Write Timing Waveform (2)** ($\overline{OE}$ Low Fixed)

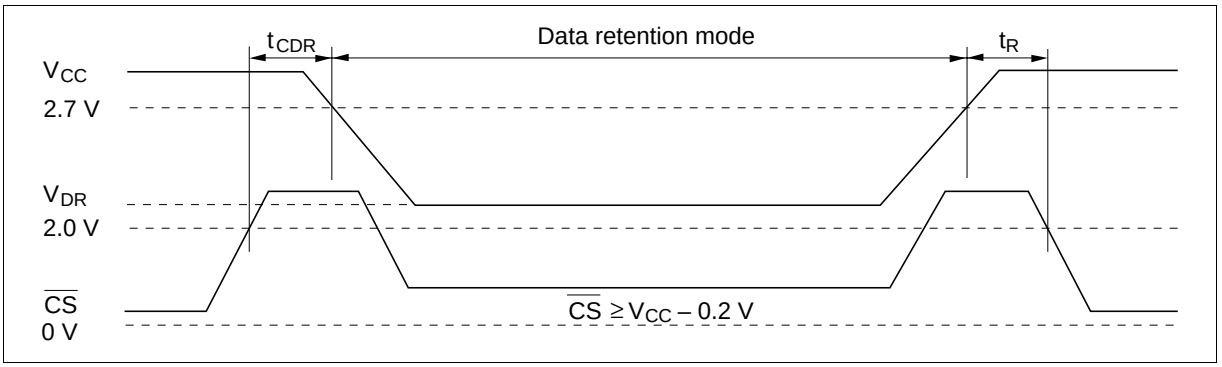


## Low $V_{CC}$ Data Retention Characteristics (Ta = –20 to +70°C)

| Parameter | Symbol | Min | Typ | Max | Unit | Test conditions*4 |
|---|---|---|---|---|---|---|
| $V_{CC}$ for data retention | $V_{DR}$ | 2 | — | — | V | $\overline{CS} \geq V_{CC} - 0.2$ V, Vin ≥ 0 V |
| Data retention current | $I_{CCDR}$ | — | 0.8*5 | 20*1 | µA | $V_{CC}$ = 3.0 V, Vin ≥ 0 V<br>$\overline{CS} \geq V_{CC} - 0.2$ V |
| | | — | 0.8*5 | 10*2 | µA | |
| | | — | 0.8*5 | 2*3 | µA | |
| Chip deselect to data retention time | $t_{CDR}$ | 0 | — | — | ns | See retention waveform |
| Operation recovery time | $t_R$ | $t_{RC}$*6 | — | — | ns | |

Notes: 1. For L-version and 10 µA (max.) at Ta = –20 to +40°C.
2. For L-SL-version and 3 µA (max.) at Ta = –20 to +40°C.
3. For L-UL-version and 2 µA (max.) at Ta = –20 to +40°C.
4. $\overline{CS}$ controls address buffer, $\overline{WE}$ buffer, $\overline{OE}$ buffer, and Din buffer. In data retention mode, Vin levels (address, $\overline{WE}$, $\overline{OE}$, I/O) can be in the high impedance state.
5. Typical values are at $V_{CC}$ = 3.0 V, Ta = +25°C and specified loading, and not guaranteed.
6. $t_{RC}$ = read cycle time.

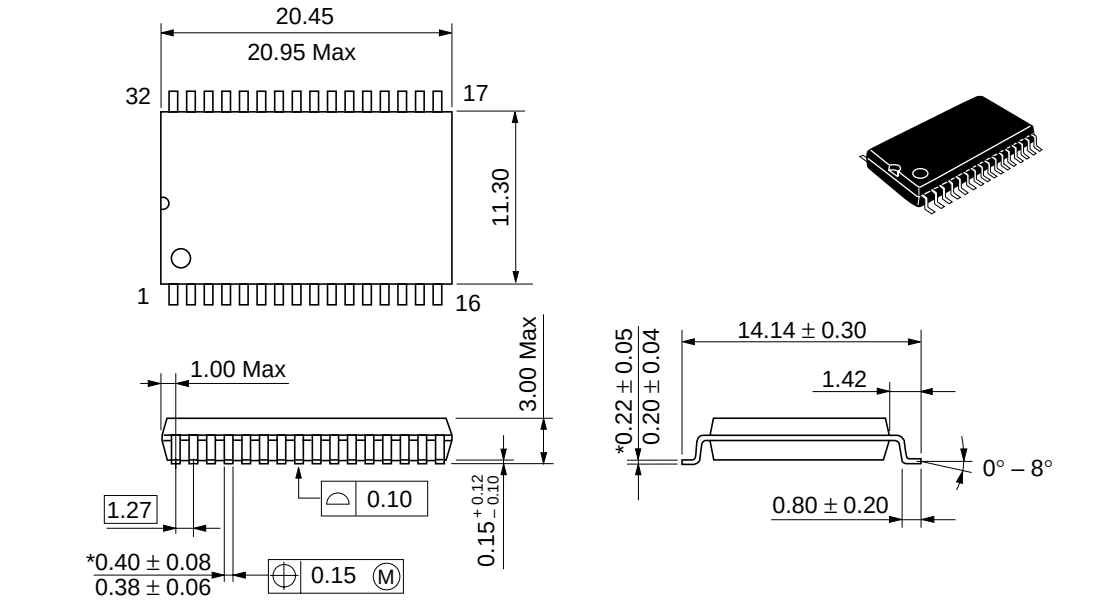
### Low $V_{CC}$ Data Retention Timing Waveform ($\overline{CS}$ Controlled)



## Package Dimensions

**HM62V8512BLFP Series** (FP-32D)

Unit: mm



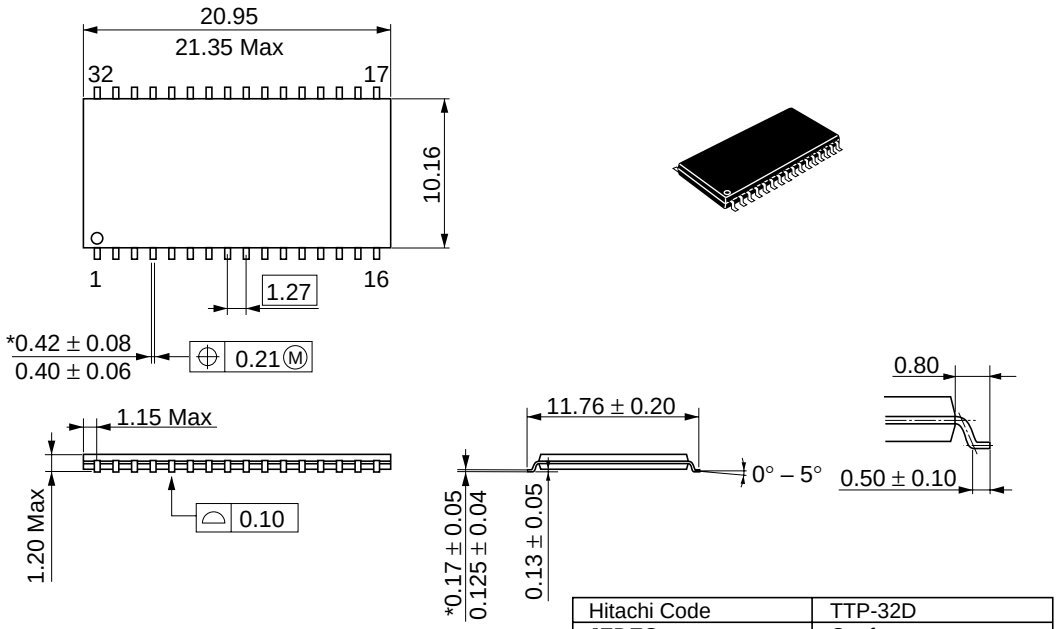

*Dimension including the plating thickness
Base material dimension

| | |
|---|---|
| Hitachi Code | FP-32D |
| JEDEC | Conforms |
| EIAJ | — |
| Weight (reference value) | 1.3 g |

## Package Dimensions (cont.)

**HM62V8512BLTT Series** (TTP-32D**)**

Unit: mm



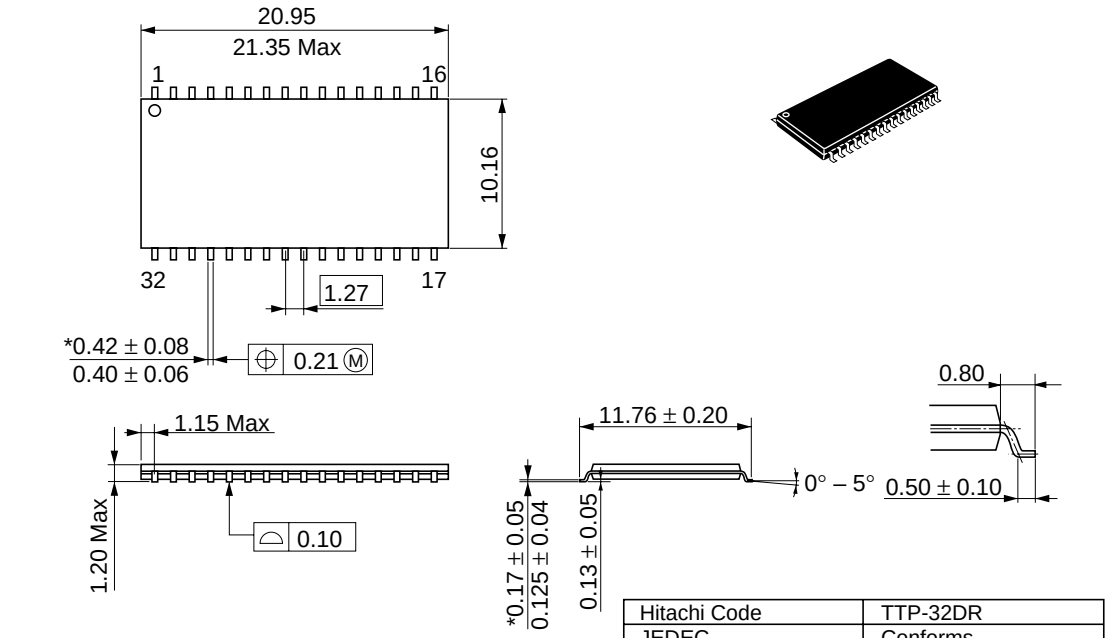

*Dimension including the plating thickness
Base material dimension

| | |
|---|---|
| Hitachi Code | TTP-32D |
| JEDEC | Conforms |
| EIAJ | — |
| Weight (reference value) | 0.51 g |

## Package Dimensions (cont.)

**HM62V8512BLRR Series** (TTP-32DR)

Unit: mm




*Dimension including the plating thickness
Base material dimension

| | |
|---|---|
| Hitachi Code | TTP-32DR |
| JEDEC | Conforms |
| EIAJ | — |
| Weight (reference value) | 0.51 g |

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HITACHI

**Hitachi, Ltd.**
Semiconductor & Integrated Circuits.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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**For further information write to:**

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive,
San Jose,CA 95134
Tel: <1> (408) 433-1990
Fax: <1>(408) 433-0223

Hitachi Europe GmbH
Electronic components Group
Dornacher Straße 3
D-85622 Feldkirchen, Munich
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.
Electronic Components Group.
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 049318
Tel: 535-2100
Fax: 535-1533

Hitachi Asia Ltd.
Taipei Branch Office
3F, Hung Kuo Building. No.167,
Tun-Hwa North Road, Taipei (105)
Tel: <886> (2) 2718-3666
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower, World Finance Centre,
Harbour City, Canton Road, Tsim Sha Tsui,
Kowloon, Hong Kong
Tel: <852> (2) 735 9218
Fax: <852> (2) 730 0281
Telex: 40815 HITEC HX